

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

(printed on: 2020-07-11 19:37:49)

**TOTAL MASS (g) : 0.032303**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002343	1000000	72532.3359375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.012783	975000	395723.78125		
		Iron (Fe)	7439-89-6	0.000315	24000	9751.46679688		
		Phosphorus (P)	7723-14-0	0.000004	300	123.828140259		
		Zinc (Zn)	7440-66-6	0.000009	700	278.613311768		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013111</b>	<b>1000000</b>	<b>405877.71875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000607	1000000	18785.8027344		
		<b>External Plating Total:</b>				<b>0.000607</b>	<b>1000000</b>	<b>18785.8027344</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000295	1000000	9132.32519531		
<b>Internal Plating Total:</b>				<b>0.000295</b>	<b>1000000</b>	<b>9132.32519531</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001034	750000	32009.5761719		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000345	250000	10680.1777344		
<b>Die Attach Total:</b>				<b>0.001379</b>	<b>1000000</b>	<b>42689.75</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.001597	110000	49438.3867188		
		Bromine (Br)	40039-93-8	0.000145	10000	4488.77050781		
		Silica (SiO2)	60676-86-0	0.012342	850000	382071.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000436	30000	13497.2675781		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.014520</b>	<b>1000000</b>	<b>449496.15625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000048	1000000	1485.93774414		
					<b>TOTAL MASS (g) :</b>	<b>0.032303</b>		